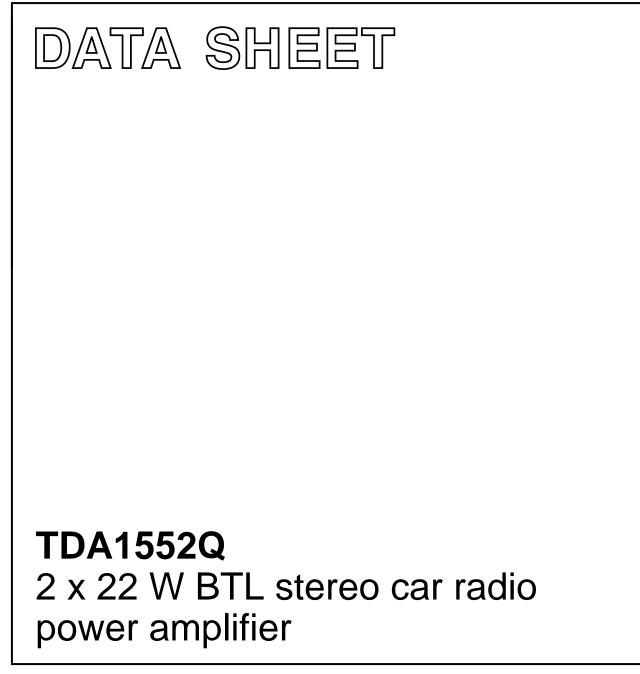
INTEGRATED CIRCUITS



Product specification File under Integrated Circuits, IC01 July 1994





GENERAL DESCRIPTION

The TDA1552Q is an integrated class-B output amplifier in a 13-lead single-in-line (SIL) plastic power package. The circuit contains 2 x 22 W amplifiers in Bridge Tied Load (BTL) configuration. The device is primarily developed for car radio applications.

Features

- Requires very few external components
- High output power
- Low offset voltage at outputs
- Fixed gain
- Good ripple rejection
- Mute/stand-by switch
- · Load dump protection
- AC and DC short-circuit-safe to ground and V_P

QUICK REFERENCE DATA

- Thermally protected
- Reverse polarity safe
- Capability to handle high energy on outputs ($V_P = 0 V$)
- Protected against electrostatic discharge
- No switch-on/switch-off plop
- Low thermal resistance
- Flexible leads.

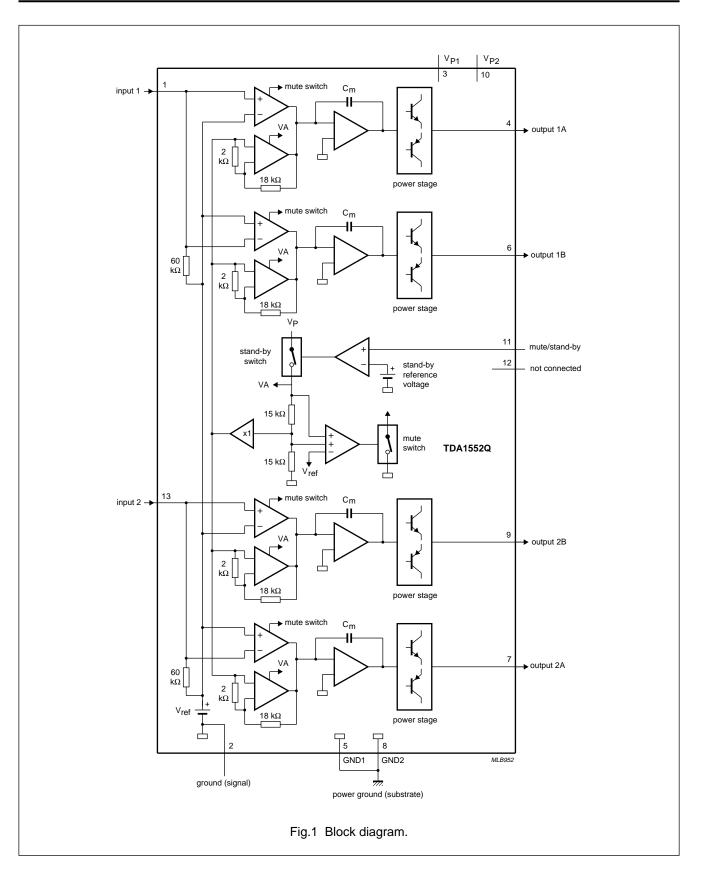
PARAMETER	CONDITIONS	SYMBOL	MIN.	TYP.	MAX.	UNIT
Supply voltage range						
operating		VP	6.0	14.4	18.0	V
non-operating		V _P	-	_	30	V
load dump protected		V _P	-	_	45	V
Repetitive peak output						
current		I _{ORM}	-	_	4	A
Total quiescent current		I _{tot}	-	80	160	mA
Stand-by current		I _{sb}	_	0.1	100	μA
Switch-on current		I _{sw}	-	_	60	μA
Input impedance		Z _I	50	60	75	kΩ
Junction temperature		Тј	-	_	150	°C
Stereo application						
Output power	$R_{L} = 4 \Omega$; THD = 10%	Po	20	22	_	W
Supply voltage ripple						
rejection	R _S = 0 Ω					
	f = 100 Hz to 10 kHz	RR	48	_	_	dB
DC output offset voltage		∆V _O	_	_	150	mV
Channel separation		α	40	_	_	dB
Channel unbalance		∆G _v	_	_	1	dB

PACKAGE OUTLINE

13-lead SIL-bent-to-DIL; plastic power (SOT141R); SOT 141-6; 1996 July 23.

TDA1552Q

2 x 22 W BTL stereo car radio power amplifier



Product specification

2 x 22 W BTL stereo car radio power amplifier

PINNING

1	IP1	input 1	8	GND2	power ground 2 (substrate)
2	GND	ground (signal)	9	OUT2B	output 2B
3	V _{P1}	positive supply voltage 1	10	V _{P2}	positive supply voltage 2
4	OUT1A	output 1A	11	M/SS	mute/stand-by switch
5	GND1	power ground 1 (substrate)	12	n.c.	not connected
6	OUT1B	output 1B	13	IP2	input 2
7	OUT2A	output 2A			

FUNCTIONAL DESCRIPTION

The TDA1552Q contains two identical amplifiers with differential input stages and can be used for bridge applications. The gain of each amplifier is fixed at 26 dB. A special feature of this device is:

Mute/stand-by switch

- low stand-by current (< 100 μA)
- low mute/stand-by switching current (low cost supply switch)
- mute facility.

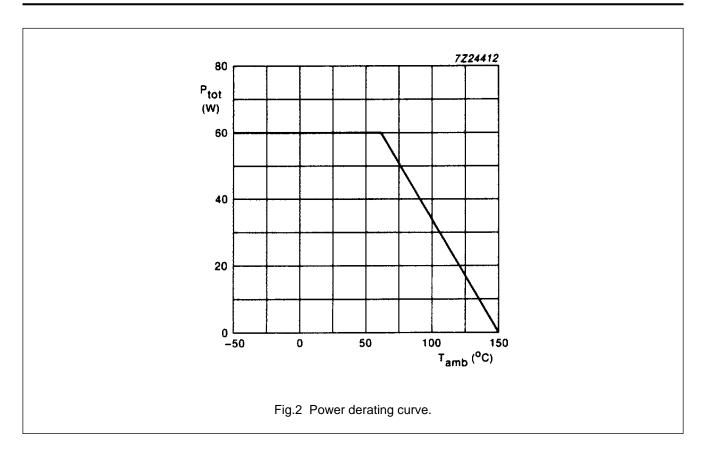
RATINGS

Limiting values in accordance with the Absolute Maximum System (IEC 134)

PARAMETER	CONDITIONS	SYMBOL	MIN.	MAX.	UNIT
Supply voltage					
operating		VP	-	18	V
non-operating		VP	-	30	V
load dump protected	during 50 ms;				
	t _r ≥ 2.5 ms	VP	-	45	V
Non-repetitive peak output current		I _{OSM}	-	6	A
Repetitive peak output current		I _{ORM}	-	4	A
Storage temperature range		T _{stg}	-55	+150	°C
Junction temperature		Tj	-	150	°C
AC and DC short-circuit-safe voltage		V _{PSC}	-	18	V
Energy handling capability at outputs	$V_{P} = 0 V$		-	200	mJ
Reverse polarity		V _{PR}	-	6	V
Total power dissipation	see Fig.2	P _{tot}	-	60	W

TDA1552Q

2 x 22 W BTL stereo car radio power amplifier



Product specification

TDA1552Q

DC CHARACTERISTICS

 V_P = 14.4 V; T_{amb} = 25 °C; measurements taken using Fig.3; unless otherwise specified

PARAMETER	CONDITIONS	SYMBOL	MIN.	TYP.	MAX.	UNIT
Supply						
Supply voltage range	note 1	VP	6.0	14.4	18.0	V
Total quiescent current		I _{tot}	-	80	160	mA
DC output voltage	note 2	Vo	-	6.9	-	V
DC output offset voltage		$ \Delta V_O $	-	-	150	mV
Mute/stand-by switch						
Switch-on voltage level		V _{ON}	8.5	_	_	V
Mute condition		V _{mute}	3.3	-	6.4	V
Output signal in mute	V _I = 1 V (max);					
position	f = 1 kHz	Vo	-	_	2	mV
DC output offset voltage						
(between pins 4 to 6 and 7 to 9)		$ \Delta V_O $	-	_	150	mV
Stand-by condition		V _{sb}	0	-	2	V
DC current in	V _{II} < 0.5 V	I _{sb}	_	_	100	μA
stand-by condition	$0.5 \text{ V} \le \text{V}_{ } < 2 \text{ V}$	I _{sb}	-	_	500	μA
Switch-on current		I _{sw}	-	25	60	μA
Supply current	short-circuit					
	to GND					
	note 3	I _P	-	5.5	-	mA

TDA1552Q

AC CHARACTERISTICS

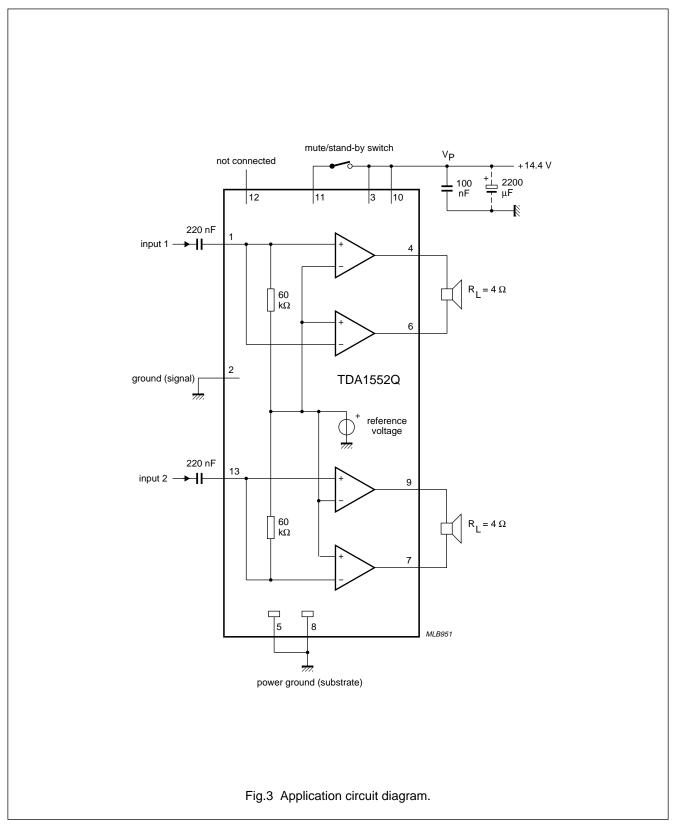
 V_P = 14.4 V; R_L = 4 Ω ; f = 1 kHz; T_{amb} = 25 °C; measurements taken using Fig.3; unless otherwise specified

PARAMETER	CONDITIONS	SYMBOL	MIN.	TYP.	MAX.	UNIT
Output power	THD = 0.5%	Po	15	17	-	W
	THD = 10%	Po	20	22	_	W
Output power at V _P = 13.2 V	THD = 0.5%	Po	_	12	_	W
	THD = 10%	Po	_	17	-	W
Total harmonic distortion	P _o = 1 W	THD	_	0.1	-	%
Power bandwidth	THD = 0.5%					
	$P_o = -1 dB$					
	w.r.t. 15 W	B _w	-	20 to	-	Hz
				15000		
Low frequency roll-off	note 4					
	–1 dB	fL	-	25	-	Hz
High frequency roll-off	–1 dB	f _H	20	-	-	kHz
Closed loop voltage gain		G _v	25	26	27	dB
Supply voltage ripple rejection	notes 5, 6	RR	42	-	-	dB
ON	notes 5, 7	RR	48	-	-	dB
mute	notes 5, 6, 7	RR	48	-	-	dB
stand-by	notes 5, 6, 7	RR	80	-	-	dB
Input impedance		Z _i	50	60	75	kΩ
Noise output voltage						
(RMS value)						
ON	R _S = 0 Ω; note 8	V _{no(rms)}	-	70	120	μV
ON	R _S = 10 kΩ; note 8	V _{no(rms)}	-	100	-	μV
mute	notes 8, 9	V _{no(rms)}	-	60	-	μA
Channel separation		α	40	-	-	dB
Channel unbalance		∆G _v	-	-	1	dB

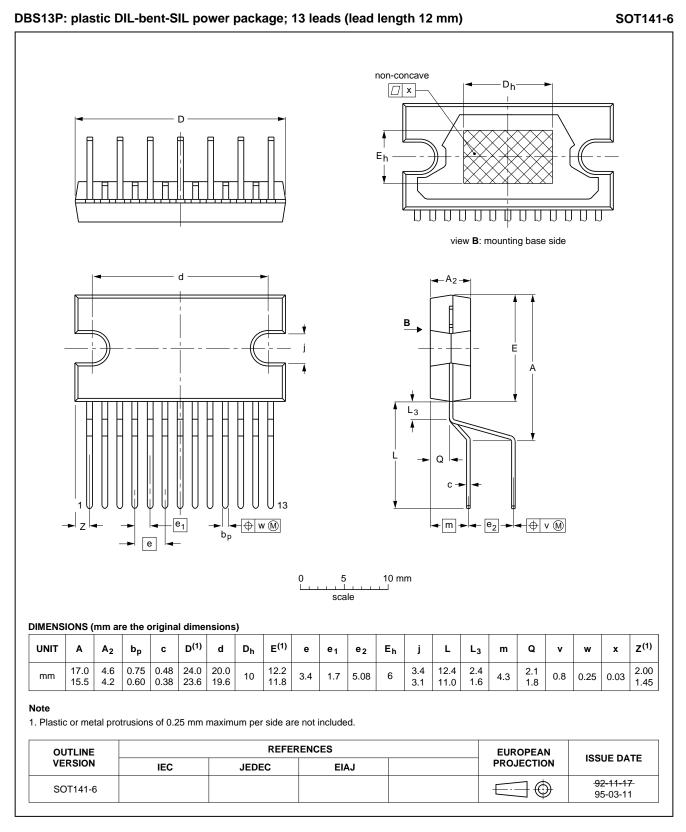
Notes to the characteristics

- 1. The circuit is DC adjusted at V_P = 6 V to 18 V and AC operating at V_P = 8.5 V to 18 V.
- 2. At 18 V < V_P < 30 V the DC output voltage \leq V_P/2.
- 3. Conditions:
 - a) V₁₁ = 0 V
 - b) short-circuit to GND
 - c) switch V₁₁ to MUTE or ON condition (rise time \geq 10 $\mu s).$
- 4. Frequency response externally fixed.
- 5. Ripple rejection measured at the output with a source impedance of 0 Ω (maximum ripple amplitude of 2 V).
- 6. Frequency f = 100 Hz.
- 7. Frequency between 1 kHz and 10 kHz.
- 8. Noise voltage measured in a bandwidth of 20 Hz to 20 kHz.
- 9. Noise output voltage independent of $R_S (V_I = 0 V)$.

APPLICATION INFORMATION



PACKAGE OUTLINE



SOLDERING

Introduction

There is no soldering method that is ideal for all IC packages. Wave soldering is often preferred when through-hole and surface mounted components are mixed on one printed-circuit board. However, wave soldering is not always suitable for surface mounted ICs, or for printed-circuits with high population densities. In these situations reflow soldering is often used.

This text gives a very brief insight to a complex technology. A more in-depth account of soldering ICs can be found in our *"IC Package Databook"* (order code 9398 652 90011).

Soldering by dipping or by wave

The maximum permissible temperature of the solder is 260 °C; solder at this temperature must not be in contact with the joint for more than 5 seconds. The total contact time of successive solder waves must not exceed 5 seconds.

The device may be mounted up to the seating plane, but the temperature of the plastic body must not exceed the specified maximum storage temperature ($T_{stg max}$). If the printed-circuit board has been pre-heated, forced cooling may be necessary immediately after soldering to keep the temperature within the permissible limit.

Repairing soldered joints

Apply a low voltage soldering iron (less than 24 V) to the lead(s) of the package, below the seating plane or not more than 2 mm above it. If the temperature of the soldering iron bit is less than 300 °C it may remain in contact for up to 10 seconds. If the bit temperature is between 300 and 400 °C, contact may be up to 5 seconds.

DEFINITIONS

Data sheet status	
Objective specification	This data sheet contains target or goal specifications for product development.
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.
Product specification	This data sheet contains final product specifications.
Limiting values	
more of the limiting values i of the device at these or at	accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or may cause permanent damage to the device. These are stress ratings only and operation any other conditions above those given in the Characteristics sections of the specification limiting values for extended periods may affect device reliability.
Application information	
Where explication informati	on is given, it is advisory and does not form part of the specification

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LIFE SUPPORT APPLICATIONS

These products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips for any damages resulting from such improper use or sale.

July 1994